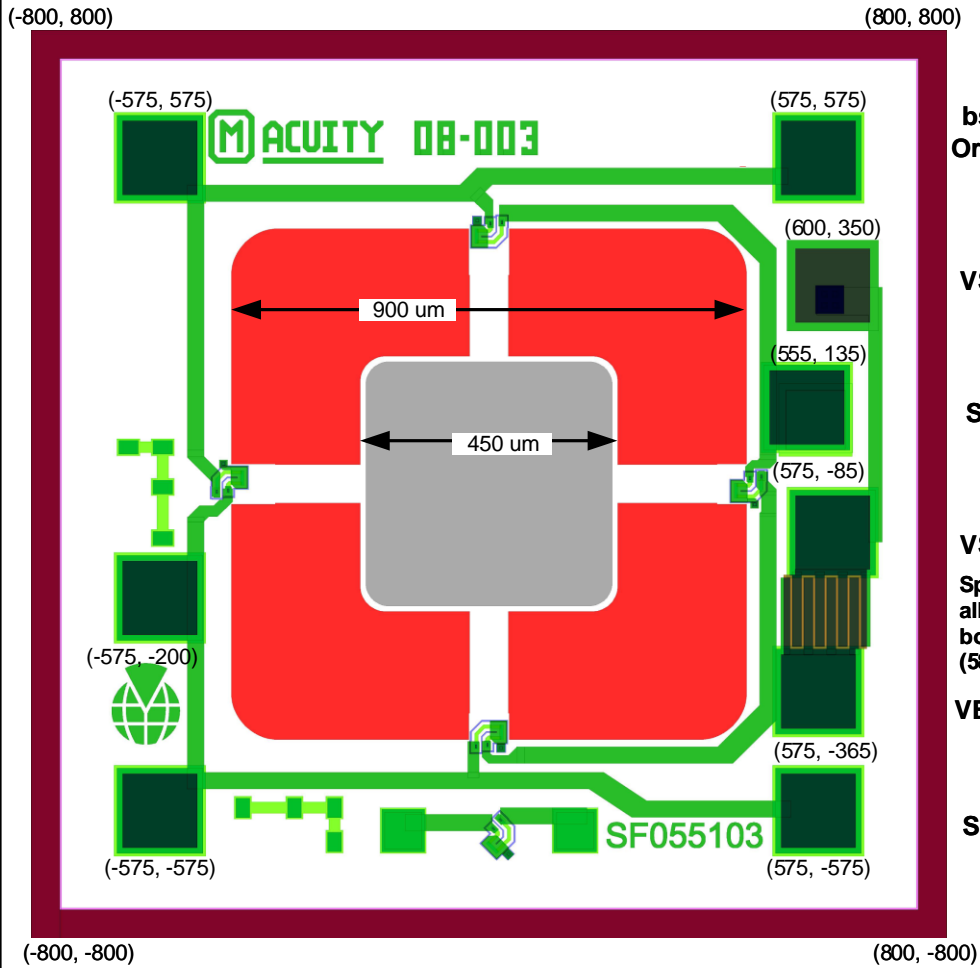


Dimensions



**bsink
Or Gnd**

VSUB

SIG -

VSUB

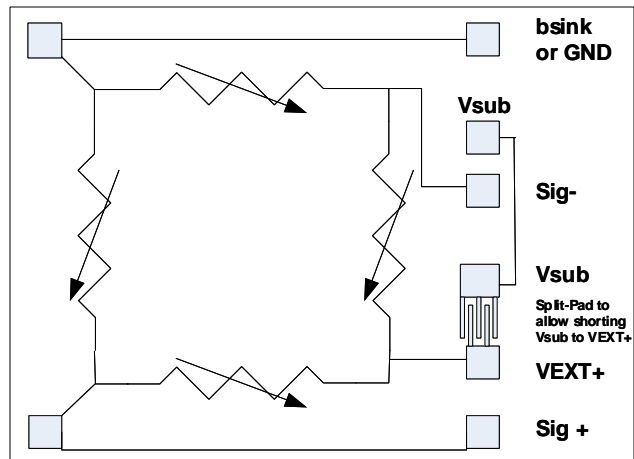
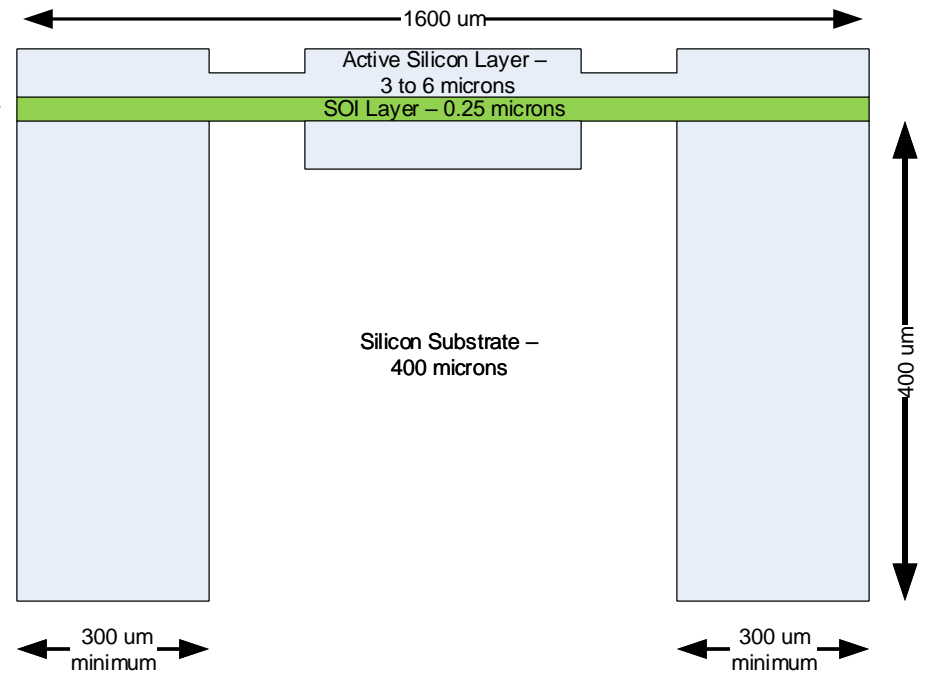
**Split-Pad to
allow single
bond at
(587.5, 225)**

VEXT+

SIG +

NOTE:

1. All dimensions are in um.
2. The coordinates for the center of each pad, shown as (XXX,YYY), are with respect to the center of the die.
3. Pad size openings are 130 X 130 um.
3. + Signal increases and – Signal decreases when pressure is applied from the top of the die.
4. Closed Bridge Configuration.
5. Compatible with direct wirebonds to ASICs such as the ZMD31010, ZMD31014, and ZMD31050.
6. For maximum performance, VSub (Pad 8) should be tied to the highest voltage in the circuit. This can be achieved with one bond using the split pad.



**Equivalent Circuit
and Pad-outs**

Acuity Incorporated
Fremont CA 94539 USA
www.acuitymicro.com



Acuity Incorporated

AC3031 Series
Dimensions and Pin-outs

Date: 21 Sept 2017

By: HVAllen

Revision: B